ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	nnockburn, Illinois. A	ll rights reserved un tions.	nder both This doc level par	ument is a decision of the declaration of the decla	claration tion end	n of the substance compasses all low	es within the manufactur ver level materials for w	er listed it hich the m	tem. Note: if nanufacturer l	the item is an as	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form 7 http://www.ipc.org/IPC-175x Distrib			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information			
Supplier Information											
Company name* Company unique ID				Unique ID Authority				Response Date*			
semi								2023-06-08			
Contact Name	t Name Title - Contact			Phone - Contact*				Email - Contact*			
oduct-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro Complian				NA	NA			Product-Env-Stewards@onsemi.com			
Requester Item Number M	Ifr Item Number	mber Mfr Item Name		Effective	Date	Version	Manufacturing Site		Weight*	UOM	Unit Type
N	CP81109HMNTXG	1109HMNTXG Single-Phase Voltag Interface		2023-06-	08		PH1		118.03	mg	Each
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material	Terminal Plating / Grid Array Material Terminal Base Alloy J		-STD-020 MSL Rating	Peak	Proces	s Body Temperat	ure Max Time at Peak	Temperat	ure Numbe	r of Reflow Cyc	eles
Matte Tin (Sn) - annealed CU Alloy 3				260		С	30	secon	ds 3		
Comments											
ATTENTION: MSL 3 Rated item requires Bake	e and Dry Pack (after	electrical test)									
For more information regarding material compo	osition please refer to	page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rinto a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.48	mg	Supplier	Silicon (Si)	7440-21-3		3.48	mg
Die Attach Solder	3.37	mg	Supplier	Silver (Ag)	7440-22-4		0.0842	mg
			А	Lead (Pb)	7439-92-1	7a	3.1172	mg
			Supplier	Tin (Sn)	7440-31-5		0.1685	mg
Lead Frame	57.28	mg	Supplier	Silver (Ag)	7440-22-4		0.2291	mg
			Supplier	Tin (Sn)	7440-31-5		0.1432	mg
			Supplier	Zinc (Zn)	7440-66-6		0.126	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1432	mg
			Supplier	Copper (Cu)	7440-50-8		56.6385	mg
Mold Compound-Black	49.82	mg		Epoxy Phenol Resin	proprietary data		5.2311	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.5889	mg
Plating	2.76	mg	Supplier	Tin (Sn)	7440-31-5		2.76	mg
Wire Bond - Au	1.32	mg	Supplier	Gold (Au)	7440-57-5		1.32	mg